

REWORK METHODS FOR LEAD FREE BGA/CGA

ABSTRACT OF THE DISCLOSURE

A method and apparatus are provided for reworking electronic component
5 assemblies where the components are joined by solder interconnections. A cutting
device employing a heated wire, blade or other cutting element is forced against and
through the solder interconnections to sever the interconnections. A preferred cutting
device employs moving the cutting element transverse to the solder interconnections to
also provide a sawing action to the solder interconnections. Another cutting device
10 employs a water jet to provide a high pressure stream of water that cuts and severs
the solder interconnections.

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